

Surface Mount Fast Recovery Rectifiers

FEATURES

- Glass passivated junction chip
- Ideal for automated placement
- High temperature metallurgically bonded construction
- Fast switching for high efficiency
- Moisture sensitivity level: level 1, per J-STD-020
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21 definition



Sub SMA



MECHANICAL DATA

Case: Sub SMA

Molding compound, UL flammability classification rating 94V-0

Base P/N with suffix "G" on packing code - green compound (halogen-free)

Base P/N with prefix "H" on packing code - AEC-Q101 qualified

Terminal: Matte tin plated leads, solderable per JESD22-B102

Meet JESD 201 class 1A whisker test

with prefix "H" on packing code meet JESD 201 class 2 whisker test

Polarity: Indicated by cathode band

Weight: 0.019 g (approximately)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS (T _A =25°C unless otherwise noted)									
PARAMETER	SYMBOL	RSF AL	RSF BL	RSF DL	RSF GL	RSF JL	RSF KL	RSF ML	UNIT
Marking code		FAL	FBL	FDL	FGL	FJL	FKL	FML	
Maximum repetitive peak reverse voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current	I _{F(AV)}	0.5							A
Peak forward surge current, 8.3 ms single half sine-wave superimposed on rated load	I _{FSM}	10							A
Maximum instantaneous forward voltage (Note 1) @ 0.5 A	V _F	1.3							V
Maximum reverse current @ rated VR T _J =25 °C T _J =125 °C	I _R	5 50							μA
Typical junction capacitance (Note 2)	C _j	4							pF
Maximum reverse recovery time (Note 3)	T _{rr}	150			250		500		ns
Typical thermal resistance	R _{θjC} R _{θjA}	32 150							°C/W
Operating junction temperature range	T _J	- 55 to +150							°C
Storage temperature range	T _{STG}	- 55 to +150							°C

Note 1: Pulse test with PW=300μs, 1% duty cycle

Note 2: Measured at 1 MHz and Applied VR=4.0 Volts.

Note 3: Reverse Recovery Test Conditions: I_F=0.5A, I_R=1.0A, I_{RR}=0.25A

ORDERING INFORMATION					
PART NO.	AEC-Q101 QUALIFIED	PACKING CODE	GREEN COMPOUND CODE	PACKAGE	PACKING
RSF _x L (Note 1)	Prefix "H"	RU	Suffix "G"	Sub SMA	1,800 / 7" Plastic reel (8mm tape)
		RV		Sub SMA	3,000 / 7" Plastic reel (8mm tape)
		RT		Sub SMA	7,500 / 13" Paper reel (8mm tape)
		MT		Sub SMA	7,500 / 13" Plastic reel (8mm tape)
		RQ		Sub SMA	10,000 / 13" Paper reel (8mm tape)
		MQ		Sub SMA	10,000 / 13" Plastic reel (8mm tape)
		R3		Sub SMA	1,800 / 7" Plastic reel (12mm tape)
		RF		Sub SMA	3,000 / 7" Plastic reel (12mm tape)
		R2		Sub SMA	7,500 / 13" Paper reel (12mm tape)
		M2		Sub SMA	7,500 / 13" Plastic reel (12mm tape)
		RH		Sub SMA	10,000 / 13" Paper reel (12mm tape)
		MH		Sub SMA	10,000 / 13" Plastic reel (12mm tape)

Note 1: "x" defines voltage from 50V (RSFAL) to 1000V (RSFML)

EXAMPLE					
PREFERRED P/N	PART NO.	AEC-Q101 QUALIFIED	PACKING CODE	GREEN COMPOUND CODE	DESCRIPTION
RSFML RU	RSFML		RU		
RSFML RUG	RSFML		RU	G	Green compound
RSFMLHRU	RSFML	H	RU		AEC-Q101 qualified

RATINGS AND CHARACTERISTICS CURVES

(TA=25°C unless otherwise noted)

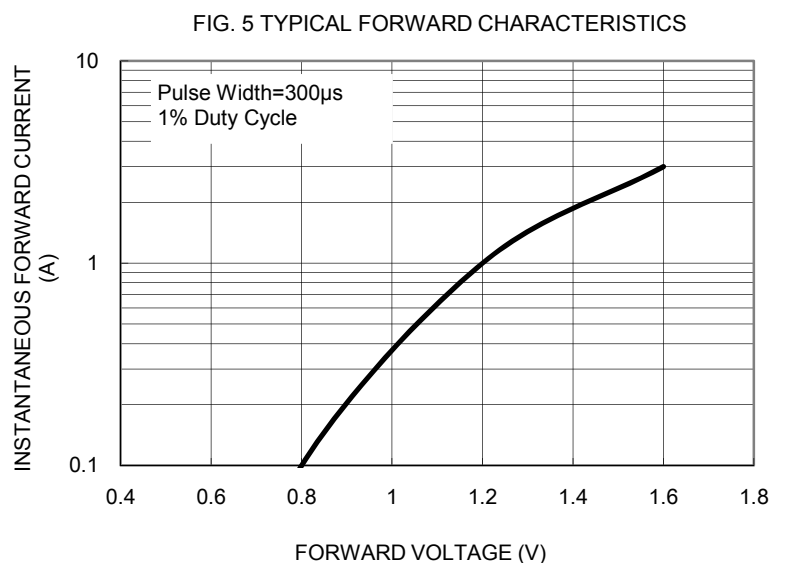
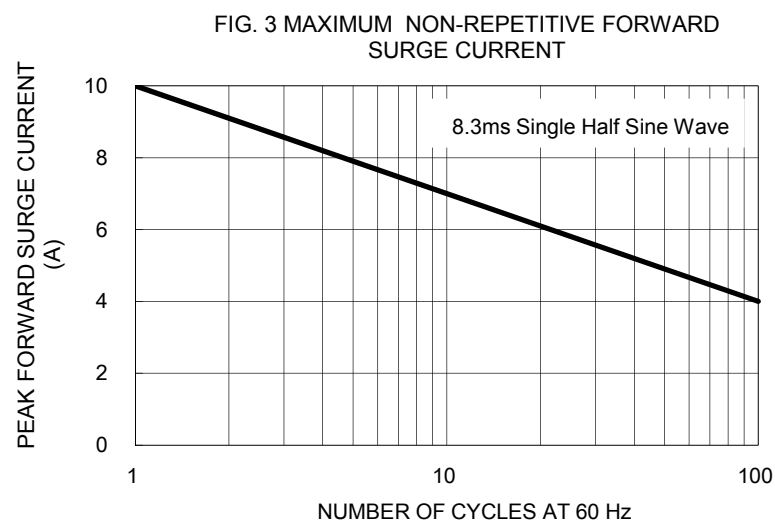
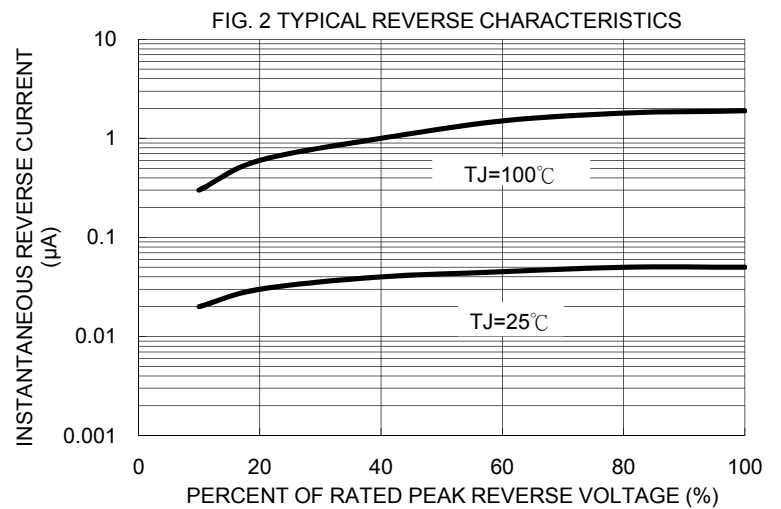
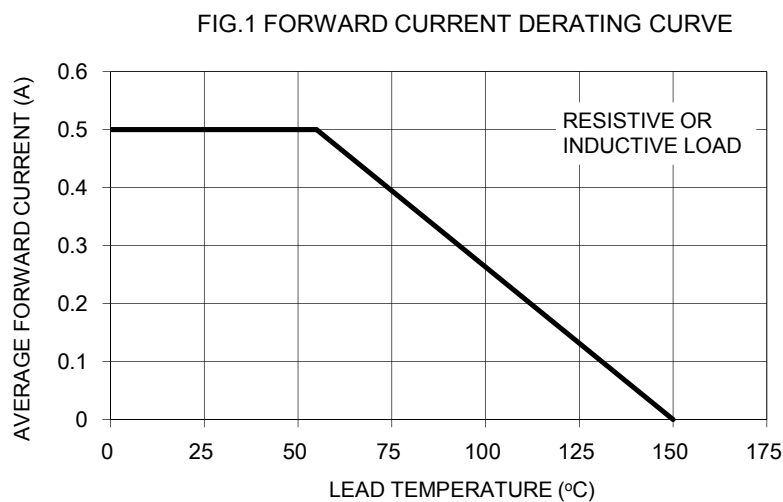


FIG. 5 TYPICAL JUNCTION CAPACITANCE

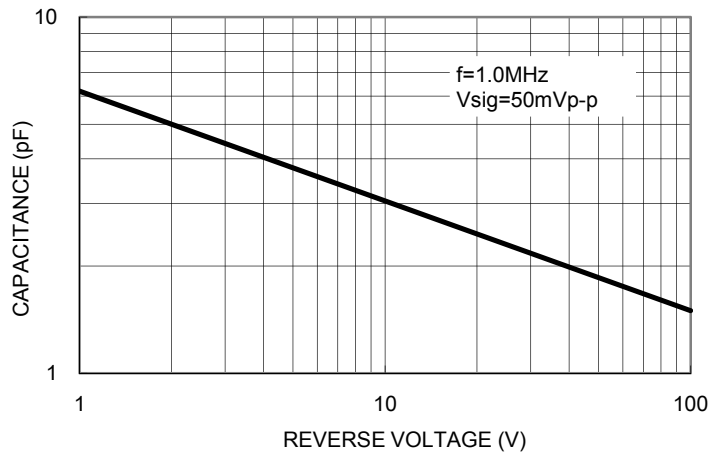
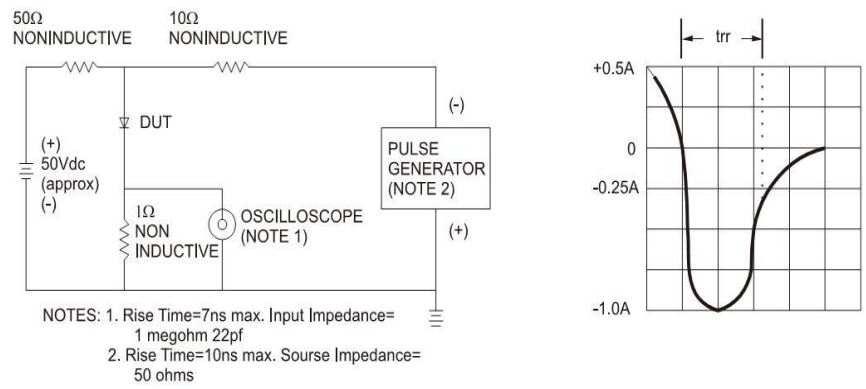
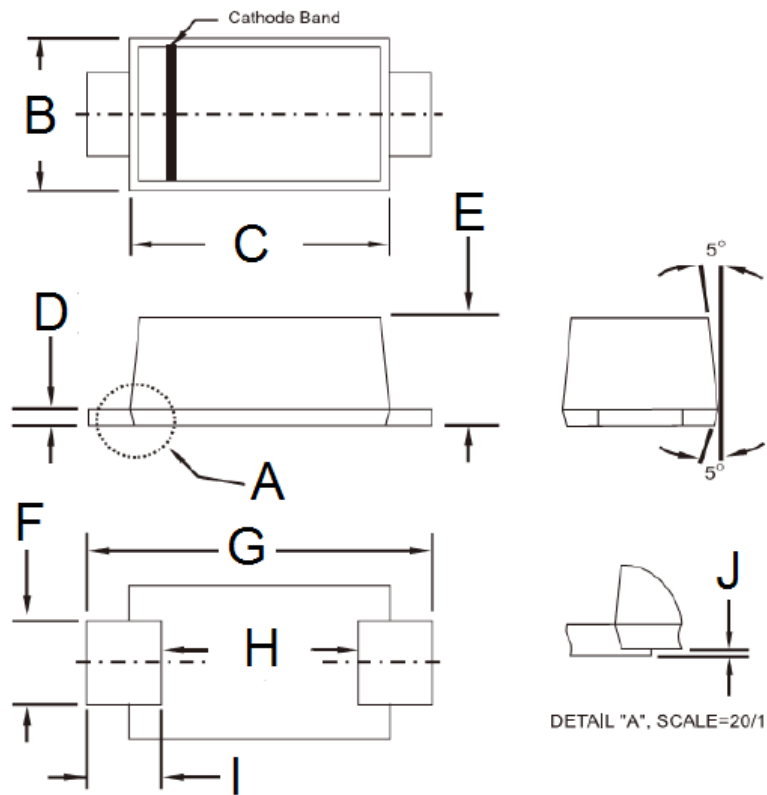


FIG.6- REVERSE RECOVERY TIME CHARACTERISTIC AND TEST CIRCUIT DIAGRAM

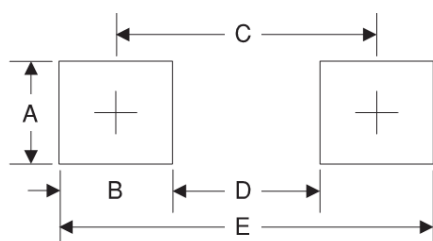


PACKAGE OUTLINE DIMENSIONS



DIM.	Unit (mm)		Unit (inch)	
	Min	Max	Min	Max
B	1.70	1.90	0.067	0.075
C	2.70	2.90	0.106	0.114
D	0.16	0.30	0.006	0.012
E	1.23	1.43	0.048	0.056
F	0.80	1.20	0.031	0.047
G	3.40	3.80	0.134	0.150
H	2.45	2.60	0.096	0.102
I	0.35	0.85	0.014	0.033
J	0.00	0.10	0.000	0.004

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	1.4	0.055
B	1.2	0.047
C	3.1	0.122
D	1.9	0.075
E	4.3	0.169

MARKING DIAGRAM



- P/N = Marking Code
- G = Green Compound
- YW = Date Code
- F = Factory Code